

with resin is defined.

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104. The mold for fabricating the semiconductor device as claimed in claim 103, further comprising an excess resin removing mechanism provided in the mold used in a resin sealing step,

wherein the excess resin removing mechanism removes excess resin and controls a pressure applied to the sealing resin in the mold.

105. The mold for fabricating the semiconductor device as claimed in claim 103, further comprising an attachment/detachment mechanism which attaches the substrate to a position of the first half body and detaches the substrate therefrom.

106. The mold for fabricating the semiconductor device as claimed in claim 105, wherein the attachment/detachment mechanism comprises:

a porous member arranged in the position of the first half body onto which the substrate is loaded; and

an intake/exhaust device performing a gas suction and supply process for the porous member.

107. The mold for fabricating the semiconductor device as claimed in claim 103, wherein an area enclosed by the second half body is wider than an area of an upper portion of the first half body in a state in which the cavity is formed.

108. A method for fabricating a semiconductor device comprising:

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a mold preparing step of preparing a mold including a first mold, and a second mold which is located so as to face the first mold, the second mold including a first half body having a shape corresponding to a shape of a substrate, and a second half body which is provided so as to surround the first half body and can be elevated with respect to the first half body, the first and second half bodies cooperating with each other so that a cavity to be filled with resin is defined;

a resin sealing step of placing the substrate on which a plurality of semiconductor elements equipped with protruding electrodes are formed in the mold and supplying resin to positions in which the protruding electrodes are provided so as to form a resin layer which seals the protruding electrodes and the substrate.;

a protruding electrode exposing step of exposing at least end portions of the protruding electrodes from the resin layer; and

a separating step of cutting the substrate together with the resin layer so that the semiconductor elements are separated into each other.--

REMARKS

Claims 13-17 are canceled without prejudice or disclaimer in favor of new claims 103-108.

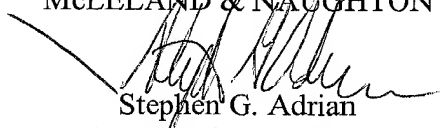
An Information Disclosure Statement is filed herewith. The Examiner is requested to acknowledge consideration of the references cited therein.

Prompt and favorable action on the merits is earnestly solicited.

In the event any fees are due with respect to this paper, please charge our Deposit Account

01-40.

Respectfully submitted,
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Attachment: Information Disclosure Statement

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